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### Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

### **Applications of Embedded - CPLDs**

## Details

Draduct Status	Obeslata
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	2.375V ~ 2.625V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	5000
Number of I/O	164
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7256bfc256-7

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPMs), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, Synplicity, and VeriBest
- Programming support with Altera's Master Programming Unit (MPU), MasterBlaster<sup>TM</sup> serial/universal serial bus (USB) communications cable, and ByteBlasterMV<sup>TM</sup> parallel port download cable, as well as programming hardware from thirdparty manufacturers and any Jam<sup>TM</sup> STAPL File (.jam), Jam Byte-Code File (.jbc), or Serial Vector Format File (.svf)-capable incircuit tester

MAX 7000B devices are high-density, high-performance devices based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000B devices operate with a 2.5-V supply voltage and provide 600 to 10,000 usable gates, ISP, pin-to-pin delays as fast as 3.5 ns, and counter speeds up to 303.0 MHz. See Table 2.

Table 2. MAX 7000B Speed GradesNote (1)									
Device		Speed Grade							
	-3	-3 -4 -5 -7 -10							
EPM7032B	$\checkmark$		$\checkmark$	$\checkmark$					
EPM7064B	~		$\checkmark$	$\checkmark$					
EPM7128B		$\checkmark$		$\checkmark$	$\checkmark$				
EPM7256B			$\checkmark$	$\checkmark$	$\checkmark$				
EPM7512B			$\checkmark$	$\checkmark$	$\checkmark$				

#### Notes:

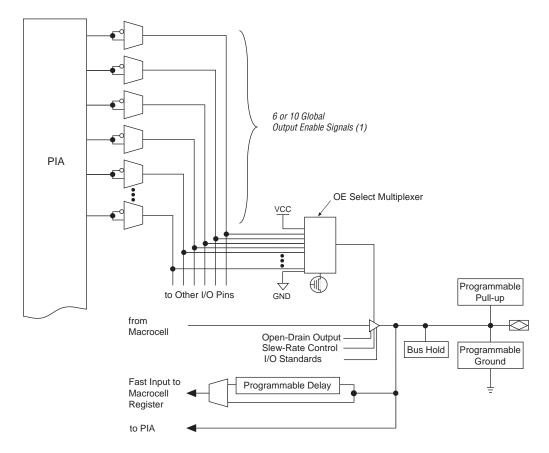
 Contact Altera Marketing for up-to-date information on available device speed grades.

The MAX 7000B architecture supports 100% TTL emulation and highdensity integration of SSI, MSI, and LSI logic functions. It easily integrates multiple devices ranging from PALs, GALs, and 22V10s to MACH and pLSI devices. MAX 7000B devices are available in a wide range of packages, including PLCC, BGA, FineLine BGA, 0.8-mm Ultra FineLine BGA, PQFP, TQFP, and TQFP packages. See Table 3.

General

Description





#### Note:

(1) EPM7032B, EPM7064B, EPM7128B, and EPM7256B devices have six output enable signals. EPM7512B devices have ten output enable signals.

When the tri-state buffer control is connected to ground, the output is tri-stated (high impedance) and the I/O pin can be used as a dedicated input. When the tri-state buffer control is connected to  $V_{CC'}$ , the output is enabled.

The MAX 7000B architecture provides dual I/O feedback, in which macrocell and pin feedbacks are independent. When an I/O pin is configured as an input, the associated macrocell can be used for buried logic.

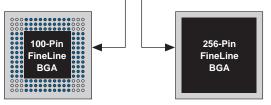
## SameFrame Pin-Outs

MAX 7000B devices support the SameFrame pin-out feature for FineLine BGA and 0.8-mm Ultra FineLine BGA packages. The SameFrame pin-out feature is the arrangement of balls on FineLine BGA and 0.8-mm Ultra FineLine BGA packages such that the lower-ball-count packages form a subset of the higher-ball-count packages. SameFrame pin-outs provide the flexibility to migrate not only from device to device within the same package, but also from one package to another. FineLine BGA packages are compatible with other FineLine BGA packages, and 0.8-mm Ultra FineLine BGA packages are compatible with other 0.8-mm Ultra FineLine BGA packages. A given printed circuit board (PCB) layout can support multiple device density/package combinations. For example, a single board layout can support a range of devices from an EPM7064B device in a 100-pin FineLine BGA package.

The Altera software provides support to design PCBs with SameFrame pin-out devices. Devices can be defined for present and future use. The Altera software generates pin-outs describing how to layout a board to take advantage of this migration (see Figure 7).

Figure 7. SameFrame Pin-Out Example

Printed Circuit Board Designed for 256-Pin FineLine BGA Package



 100-Pin FineLine BGA Package (Reduced I/O Count or Logic Requirements)
 256-Pin FineLine BGA Package (Increased I/O Count or Logic Requirements)

**Altera Corporation** 

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

### Programming a Single MAX 7000B Device

The time required to program a single MAX 7000B device in-system can be calculated from the following formula:

<sup>t</sup> PROG	= t <sub>PPULSE</sub> +	<sup>Cycle</sup> ртск f <sub>TCK</sub>
where:	t <sub>PROG</sub> t <sub>PPULSE</sub>	<ul><li>Programming time</li><li>Sum of the fixed times to erase, program, and verify the EEPROM cells</li></ul>
	Cycle <sub>PTCK</sub> f <sub>TCK</sub>	<ul><li>Number of TCK cycles to program a device</li><li>TCK frequency</li></ul>

The ISP times for a stand-alone verification of a single MAX 7000B device can be calculated from the following formula:

$t_{VER} = t_{VPULSE} + \frac{C_2}{2}$	<sup>JCle</sup> VTCK <sup>f</sup> TCK
where: $t_{VER}$ $t_{VPULSE}$ $Cycle_{VTCK}$	<ul><li>= Verify time</li><li>= Sum of the fixed times to verify the EEPROM cells</li><li>= Number of TCK cycles to verify a device</li></ul>

The instruction register length of MAX 7000B devices is ten bits. The MAX 7000B USERCODE register length is 32 bits. Tables 7 and 8 show the boundary-scan register length and device IDCODE information for MAX 7000B devices.

Table 7. MAX 7000B Boundary-Scan Register Length							
Device	Boundary-Scan Register Length						
EPM7032B	96						
EPM7064B	192						
EPM7128B	288						
EPM7256B	480						
EPM7512B	624						

Table 8. 32-Bit MAX 7000B Device IDCODE       Note (1)										
Device		IDCODE (32 Bits)								
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	<b>1 (1 Bit)</b> (2)						
EPM7032B	0010	0111 0000 0011 0010	00001101110	1						
EPM7064B	0010	0111 0000 0110 0100	00001101110	1						
EPM7128B	0010	0111 0001 0010 1000	00001101110	1						
EPM7256B	0010	0111 0010 0101 0110	00001101110	1						
EPM7512B	0010	0111 0101 0001 0010	00001101110	1						

Notes:

(1) The most significant bit (MSB) is on the left.

(2) The least significant bit (LSB) for all JTAG IDCODEs is 1.

See *Application Note* 39 (IEEE 1149.1 (JTAG) *Boundary-Scan Testing in Altera Devices*) for more information on JTAG boundary-scan testing.

Figure 8 shows the timing information for the JTAG signals.

# Programmable Speed/Power Control

Output

Configuration

MAX 7000B devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000B device for either high-speed or low-power operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder ( $t_{LPA}$ ) for the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{ACL}$ ,  $t_{CPPW}$ ,  $t_{EN}$ , and  $t_{SEXP}$  parameters.

MAX 7000B device outputs can be programmed to meet a variety of system-level requirements.

## MultiVolt I/O Interface

The MAX 7000B device architecture supports the MultiVolt I/O interface feature, which allows MAX 7000B devices to connect to systems with differing supply voltages. MAX 7000B devices in all packages can be set for 3.3-V, 2.5-V, or 1.8-V pin operation. These devices have one set of  $V_{CC}$  pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The VCCIO pins can be connected to either a 3.3-V, 2.5-V, or 1.8-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 1.8-V power supply, the output levels are compatible with 1.8-V systems. When the VCCIO pins are connected to a 2.5-V power supply, the output levels are compatible with 2.5-V systems. When the VCCIO pins are connected to a 3.3-V power supply, the output high is at 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with V<sub>CCIO</sub> levels of 2.5 V or 1.8 V incur a nominal timing delay adder.

Table 10 describes the MAX 7000B MultiVolt I/O support.

### Programmable Pull-Up Resistor

Each MAX 7000B device I/O pin provides an optional programmable pull-up resistor during user mode. When this feature is enabled for an I/O pin, the pull-up resistor (typically 50 k<sup>3</sup>/<sub>4</sub>) weakly holds the output to  $V_{CCIO}$  level.

## Bus Hold

Each MAX 7000B device I/O pin provides an optional bus-hold feature. When this feature is enabled for an I/O pin, the bus-hold circuitry weakly holds the signal at its last driven state. By holding the last driven state of the pin until the next input signals is present, the bus-hold feature can eliminate the need to add external pull-up or pull-down resistors to hold a signal level when the bus is tri-stated. The bus-hold circuitry also pulls undriven pins away from the input threshold voltage where noise can cause unintended high-frequency switching. This feature can be selected individually for each I/O pin. The bus-hold output will drive no higher than  $V_{CCIO}$  to prevent overdriving signals. The propagation delays through the input and output buffers in MAX 7000B devices are not affected by whether the bus-hold feature is enabled or disabled.

The bus-hold circuitry weakly pulls the signal level to the last driven state through a resistor with a nominal resistance ( $R_{BH}$ ) of approximately 8.5 k<sup>3</sup>/<sub>4</sub>. Table 12 gives specific sustaining current that will be driven through this resistor and overdrive current that will identify the next driven input level. This information is provided for each VCCIO voltage level.

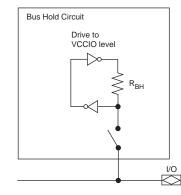
Table 12. Bus Hold Parameters									
Parameter	Conditions		VCCIO Level					Units	
		1.8 V 2.5 V 3.3 V		2.5 V 3.3 V					
		Min	Max	Min	Max	Min	Max		
Low sustaining current	$V_{IN} > V_{IL} (max)$	30		50		70		μΑ	
High sustaining current	V <sub>IN</sub> < V <sub>IH</sub> (min)	-30		-50		-70		μA	
Low overdrive current	$0 V < V_{IN} < V_{CCIO}$		200		300		500	μΑ	
High overdrive current	$0 V < V_{IN} < V_{CCIO}$		-295		-435		-680	μA	

The bus-hold circuitry is active only during user operation. At power-up, the bus-hold circuit initializes its initial hold value as  $V_{CC}$  approaches the recommended operation conditions. When transitioning from ISP to User Mode with bus hold enabled, the bus-hold circuit captures the value present on the pin at the end of programming.

Two inverters implement the bus-hold circuitry in a loop that weakly drives back to the I/O pin in user mode.

Figure 10 shows a block diagram of the bus-hold circuit.

### Figure 10. Bus-Hold Circuit



# PCI Compatibility

MAX 7000B devices are compatible with PCI applications as well as all 3.3-V electrical specifications in the *PCI Local Bus Specification Revision 2.2* except for the clamp diode. While having multiple clamp diodes on a signal trace may be redundant, designers can add an external clamp diode to meet the specification. Table 13 shows the MAX 7000B device speed grades that meet the PCI timing specifications.

Table 13. MAX 7000B Device Speed Grades that Meet PCI Timing         Specifications							
Device Specification							
	33-MHz PCI	66-MHz PCI					
EPM7032B	All speed grades	-3					
EPM7064B	All speed grades	-3					
EPM7128B	All speed grades	-4					
EPM7256B	All speed grades	-5 (1)					
EPM7512B	All speed grades	-5 (1)					

#### Note:

(1) The EPM7256B and EPM7512B devices in a -5 speed grade meet all PCI timing specifications for 66-MHz operation except the Input Setup Time to CLK—Bused Signal parameter. However, these devices are within 1 ns of that parameter. EPM7256B and EPM7512B devices meet all other 66-MHz PCI timing specifications.

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Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CCINT</sub>	Supply voltage for internal logic and input buffers	(10)	2.375	2.625	V
V <sub>CCIO</sub>	Supply voltage for output drivers, 3.3-V operation		3.0	3.6	V
	Supply voltage for output drivers, 2.5-V operation		2.375	2.625	V
	Supply voltage for output drivers, 1.8-V operation		1.71	1.89	V
V <sub>CCISP</sub>	Supply voltage during in-system programming		2.375	2.625	V
VI	Input voltage	(3)	-0.5	3.9	V
Vo	Output voltage		0	V <sub>CCIO</sub>	V
T <sub>A</sub>	Ambient temperature	For commercial use	0	70	°C
		For industrial use (11)	-40	85	°C
TJ	Junction temperature	For commercial use	0	90	°C
		For industrial use (11)	-40	105	°C
t <sub>R</sub>	Input rise time			40	ns
t <sub>F</sub>	Input fall time			40	ns

Symbol	Parameter	Conditions			Speed	Grade			Unit	
			-3	.5	-5	.0	-7.5		1	
			Min	Max	Min	Max	Min	Max		
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF (2)		3.5		5.0		7.5	ns	
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF (2)		3.5		5.0		7.5	ns	
t <sub>SU</sub>	Global clock setup time	(2)	2.1		3.0		4.5		ns	
t <sub>H</sub>	Global clock hold time	(2)	0.0		0.0		0.0		ns	
t <sub>FSU</sub>	Global clock setup time of fast input		1.0		1.0		1.5		ns	
t <sub>FH</sub>	Global clock hold time of fast input		1.0		1.0		1.0		ns	
t <sub>FZHSU</sub>	Global clock setup time of fast input with zero hold time		2.0		2.5		3.0		ns	
t <sub>FZHH</sub>	Global clock hold time of fast input with zero hold time		0.0		0.0		0.0		ns	
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF	1.0	2.4	1.0	3.4	1.0	5.0	ns	
t <sub>CH</sub>	Global clock high time		1.5		2.0		3.0		ns	
t <sub>CL</sub>	Global clock low time		1.5		2.0		3.0		ns	
t <sub>ASU</sub>	Array clock setup time	(2)	0.9		1.3		1.9		ns	
t <sub>AH</sub>	Array clock hold time	(2)	0.2		0.3		0.6		ns	
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF (2)	1.0	3.6	1.0	5.1	1.0	7.6	ns	
t <sub>ACH</sub>	Array clock high time		1.5		2.0		3.0		ns	
t <sub>ACL</sub>	Array clock low time		1.5		2.0		3.0		ns	
t <sub>CPPW</sub>	Minimum pulse width for clear and preset		1.5		2.0		3.0		ns	
<sup>t</sup> cnt	Minimum global clock period	(2)		3.3		4.7		7.0	ns	
f <sub>cnt</sub>	Maximum internal global clock frequency	(2), (3)	303.0		212.8		142.9		MHz	
t <sub>acnt</sub>	Minimum array clock period	(2)		3.3		4.7		7.0	ns	
facnt	Maximum internal array clock frequency	(2), (3)	303.0		212.8		142.9		MHz	

## Tables 18 through 32 show MAX 7000B device timing parameters.

I/O Standard	Parameter			Speed Grade				Unit
		-3.5		-5.0		-7.5		]
		Min	Мах	Min	Max	Min	Max	
3.3 V TTL/CMOS	Input to (PIA)		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns
2.5 V TTL/CMOS	Input to PIA		0.3		0.4		0.6	ns
	Input to global clock and clear		0.3		0.4		0.6	ns
	Input to fast input register		0.2		0.3		0.4	ns
	All outputs		0.2		0.3		0.4	ns
1.8 V TTL/CMOS	Input to PIA		0.5		0.8		1.1	ns
	Input to global clock and clear		0.5		0.8		1.1	ns
	Input to fast input register		0.4		0.5		0.8	ns
	All outputs		1.2		1.8		2.6	ns
SSTL-2 Class I	Input to PIA		1.3		1.9		2.8	ns
	Input to global clock and clear		1.2		1.8		2.6	ns
	Input to fast input register		0.9		1.3		1.9	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-2 Class II	Input to PIA		1.3		1.9		2.8	ns
	Input to global clock and clear		1.2		1.8		2.6	ns
	Input to fast input register		0.9		1.3		1.9	ns
	All outputs		-0.1		-0.1		-0.2	ns
SSTL-3 Class I	Input to PIA		1.2		1.8		2.6	ns
	Input to global clock and clear		0.9		1.3		1.9	ns
	Input to fast input register		0.8		1.1		1.7	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-3 Class II	Input to PIA		1.2		1.8		2.6	ns
SSTL-3 Class II	Input to global clock and clear		0.9		1.3		1.9	ns
	Input to fast input register		0.8		1.1		1.7	ns
	All outputs		0.0		0.0		0.0	ns
GTL+	Input to PIA		1.6		2.3		3.4	ns
	Input to global clock and clear		1.6		2.3		3.4	ns
	Input to fast input register		1.5		2.1		3.2	ns
	All outputs		0.0		0.0		0.0	ns

Symbol	Parameter	Conditions	Speed Grade						
			-	3	-5		-7		1
			Min	Max	Min	Max	Min	Max	1
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF (2)		3.5		5.0		7.5	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF (2)		3.5		5.0		7.5	ns
t <sub>SU</sub>	Global clock setup time	(2)	2.1		3.0		4.5		ns
t <sub>H</sub>	Global clock hold time	(2)	0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		1.0		1.0		1.5		ns
t <sub>FH</sub>	Global clock hold time of fast input		1.0		1.0		1.0		ns
t <sub>FZHSU</sub>	Global clock setup time of fast input with zero hold time		2.0		2.5		3.0		ns
t <sub>FZHH</sub>	Global clock hold time of fast input with zero hold time		0.0		0.0		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF	1.0	2.4	1.0	3.4	1.0	5.0	ns
t <sub>CH</sub>	Global clock high time		1.5		2.0		3.0		ns
t <sub>CL</sub>	Global clock low time		1.5		2.0		3.0		ns
t <sub>ASU</sub>	Array clock setup time	(2)	0.9		1.3		1.9		ns
t <sub>AH</sub>	Array clock hold time	(2)	0.2		0.3		0.6		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF (2)	1.0	3.6	1.0	5.1	1.0	7.6	ns
t <sub>ACH</sub>	Array clock high time		1.5		2.0		3.0		ns
t <sub>ACL</sub>	Array clock low time		1.5		2.0		3.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset		1.5		2.0		3.0		ns
t <sub>CNT</sub>	Minimum global clock period	(2)		3.3		4.7		7.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(2), (3)	303.0		212.8		142.9		MHz
t <sub>acnt</sub>	Minimum array clock period	(2)		3.3		4.7		7.0	ns
f <sub>acnt</sub>	Maximum internal array clock frequency	(2), (3)	303.0		212.8		142.9		MHz

I/O Standard	Parameter		Speed Grade						
		-4		-7		-10			
		Min	Max	Min	Max	Min	Max	1	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns	
	Input to global clock and clear		0.0		0.0		0.0	ns	
	Input to fast input register		0.0		0.0		0.0	ns	
	All outputs		0.0		0.0		0.0	ns	
2.5 V TTL/CMOS	Input to PIA		0.3		0.6		0.8	ns	
	Input to global clock and clear		0.3		0.6		0.8	ns	
	Input to fast input register		0.2		0.4		0.5	ns	
	All outputs		0.2		0.4		0.5	ns	
1.8 V TTL/CMOS	Input to PIA		0.5		0.9		1.3	ns	
	Input to global clock and clear		0.5		0.9		1.3	ns	
	Input to fast input register		0.4		0.8		1.0	ns	
	All outputs		1.2		2.3		3.0	ns	
SSTL-2 Class I	Input to PIA		1.4		2.6		3.5	ns	
	Input to global clock and clear		1.2		2.3		3.0	ns	
	Input to fast input register		1.0		1.9		2.5	ns	
	All outputs		0.0		0.0		0.0	ns	
SSTL-2 Class II	Input to PIA		1.4		2.6		3.5	ns	
	Input to global clock and clear		1.2		2.3		3.0	ns	
	Input to fast input register		1.0		1.9		2.5	ns	
	All outputs		-0.1		-0.2		-0.3	ns	
SSTL-3 Class I	Input to PIA		1.3		2.4		3.3	ns	
	Input to global clock and clear		1.0		1.9		2.5	ns	
	Input to fast input register		0.9		1.7		2.3	ns	
	All outputs		0.0		0.0		0.0	ns	
SSTL-3 Class II	Input to PIA		1.3		2.4		3.3	ns	
	Input to global clock and clear		1.0		1.9		2.5	ns	
	Input to fast input register		0.9	1	1.7		2.3	ns	
	All outputs		0.0	1	0.0		0.0	ns	
GTL+	Input to PIA		1.7		3.2		4.3	ns	
	Input to global clock and clear		1.7		3.2		4.3	ns	
	Input to fast input register		1.6		3.0		4.0	ns	
	All outputs		0.0		0.0		0.0	ns	

I/O Standard	Parameter		Speed Grade						
		-5		-7		-10		1	
		Min	Max	Min	Max	Min	Max	1	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns	
	Input to global clock and clear		0.0		0.0		0.0	ns	
	Input to fast input register		0.0		0.0		0.0	ns	
	All outputs		0.0		0.0		0.0	ns	
2.5 V TTL/CMOS	Input to PIA		0.4		0.6		0.8	ns	
	Input to global clock and clear		0.3		0.5		0.6	ns	
	Input to fast input register		0.2		0.3		0.4	ns	
	All outputs		0.2		0.3		0.4	ns	
1.8 V TTL/CMOS	Input to PIA		0.6		0.9		1.2	ns	
	Input to global clock and clear		0.6		0.9		1.2	ns	
	Input to fast input register		0.5		0.8		1.0	ns	
	All outputs		1.3		2.0		2.6	ns	
SSTL-2 Class I	Input to PIA		1.5		2.3		3.0	ns	
	Input to global clock and clear		1.3		2.0		2.6	ns	
	Input to fast input register		1.1		1.7		2.2	ns	
	All outputs		0.0		0.0		0.0	ns	
SSTL-2 Class II	Input to PIA		1.5		2.3		3.0	ns	
	Input to global clock and clear		1.3		2.0		2.6	ns	
	Input to fast input register		1.1		1.7		2.2	ns	
	All outputs		-0.1		-0.2		-0.2	ns	
SSTL-3 Class I	Input to PIA		1.4		2.1		2.8	ns	
	Input to global clock and clear		1.1		1.7		2.2	ns	
	Input to fast input register		1.0		1.5		2.0	ns	
	All outputs		0.0		0.0		0.0	ns	
SSTL-3 Class II	Input to PIA		1.4		2.1		2.8	ns	
	Input to global clock and clear		1.1		1.7		2.2	ns	
	Input to fast input register		1.0		1.5		2.0	ns	
	All outputs		0.0		0.0		0.0	ns	
GTL+	Input to PIA		1.8		2.7		3.6	ns	
	Input to global clock and clear		1.8	l	2.7		3.6	ns	
	Input to fast input register		1.7		2.6		3.4	ns	
	All outputs		0.0	1	0.0		0.0	ns	

Table 29. EPM7256B Selectable I/O Standard Timing Adder Delays (Part 2 of 2)       Note (1)										
I/O Standard	Parameter	Speed Grade								
		-5 -7		-1	-10					
		Min	Max	Min	Max	Min	Max			
PCI	Input to PIA		0.0		0.0		0.0	ns		
	Input to global clock and clear		0.0		0.0		0.0	ns		
	Input to fast input register		0.0		0.0		0.0	ns		
	All outputs		0.0		0.0		0.0	ns		

#### Notes to tables:

(1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.

(2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(4) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{ACL}$ ,  $t_{CPPW}$ ,  $t_{EN}$ , and  $t_{SEXP}$  parameters for macrocells running in low-power mode.

I/O Standard	Parameter		Speed Grade						
		-5		-7		-10		1	
		Min	Max	Min	Max	Min	Max	1	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns	
	Input to global clock and clear		0.0		0.0		0.0	ns	
	Input to fast input register		0.0		0.0		0.0	ns	
	All outputs		0.0		0.0		0.0	ns	
2.5 V TTL/CMOS	Input to PIA		0.4		0.5		0.7	ns	
	Input to global clock and clear		0.3		0.4		0.5	ns	
	Input to fast input register		0.2		0.3		0.3	ns	
	All outputs		0.2		0.3		0.3	ns	
1.8 V TTL/CMOS	Input to PIA		0.7		1.0		1.3	ns	
	Input to global clock and clear		0.6		0.8		1.0	ns	
	Input to fast input register		0.5		0.6		0.8	ns	
	All outputs		1.3		1.8		2.3	ns	
SSTL-2 Class I	Input to PIA		1.5		2.0		2.7	ns	
	Input to global clock and clear		1.4		1.9		2.5	ns	
	Input to fast input register		1.1		1.5		2.0	ns	
	All outputs		0.0		0.0		0.0	ns	
SSTL-2 Class II	Input to PIA		1.5		2.0		2.7	ns	
	Input to global clock and clear		1.4		1.9		2.5	ns	
	Input to fast input register		1.1		1.5		2.0	ns	
	All outputs		-0.1		-0.1		-0.2	ns	
SSTL-3 Class I	Input to PIA		1.4		1.9		2.5	ns	
	Input to global clock and clear		1.2		1.6		2.2	ns	
	Input to fast input register		1.0		1.4		1.8	ns	
	All outputs		0.0		0.0		0.0	ns	
SSTL-3 Class II	Input to PIA		1.4		1.9		2.5	ns	
	Input to global clock and clear		1.2		1.6		2.2	ns	
	Input to fast input register		1.0		1.4		1.8	ns	
	All outputs		0.0		0.0		0.0	ns	
GTL+	Input to PIA		1.8		2.5		3.3	ns	
	Input to global clock and clear		1.9		2.6		3.5	ns	
	Input to fast input register		1.8		2.5		3.3	ns	
	All outputs		0.0		0.0		0.0	ns	

Table 32. EPM7512B Selectable I/O Standard Timing Adder Delays (Part 2 of 2)       Note (1)										
I/O Standard	Parameter	Speed Grade								
		-5		-5 -7		-10				
		Min	Max	Min	Max	Min	Max			
PCI	Input to PIA		0.0		0.0		0.0	ns		
	Input to global clock and clear		0.0		0.0		0.0	ns		
	Input to fast input register		0.0		0.0		0.0	ns		
	All outputs		0.0		0.0		0.0	ns		

#### Notes to tables:

(1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.

(2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.12 ns to the PIA timing value.

(3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(4) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{ACL}$ ,  $t_{CPPW}$ ,  $t_{EN}$ , and  $t_{SEXP}$  parameters for macrocells running in low-power mode.

## Power Consumption

Supply power (P) versus frequency ( $f_{MAX}$ , in MHz) for MAX 7000B devices is calculated with the following equation:

 $P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$ 

The  $P_{IO}$  value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in *Application Note* 74 (*Evaluating Power for Altera Devices*).

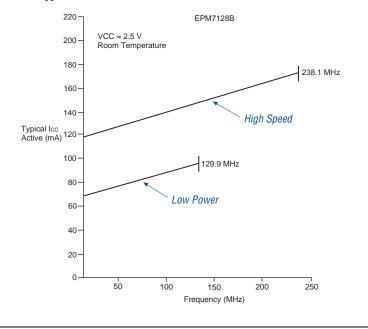
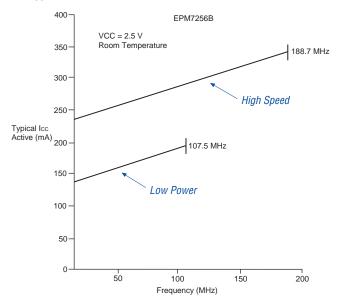


Figure 17. I<sub>CC</sub> vs. Frequency for EPM7128B Devices





### Figure 23. 100-Pin TQFP Package Pin-Out Diagram

Package outline not drawn to scale.

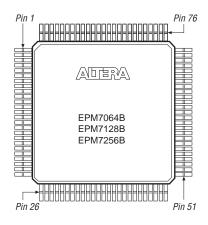


Figure 24. 100-Pin FineLine BGA Package Pin-Out Diagram

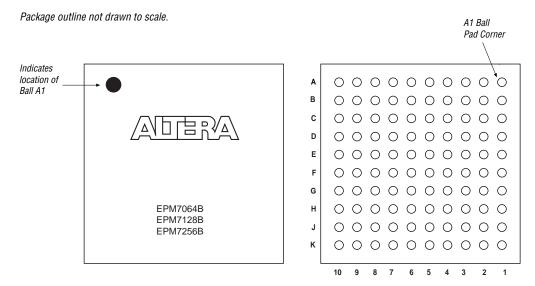


Figure 29. 256-Pin FineLine BGA Package Pin-Out Diagram

Package outline not drawn to scale.



## Revision History

The information contained in the *MAX* 7000B Programmable Logic Device Family Data Sheet version 3.5 supersedes information published in previous versions.

## Version 3.5

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.5:

■ Updated Figure 28.

## Version 3.4

The following changes were made to the *MAX* 7000B Programmable Logic Device Family Data Sheet version 3.4:

Updated text in the "Power Sequencing & Hot-Socketing" section.